

Soldering Temperature Profiles

Infrared reflow

Recommends the reflow method using far- and middle-infrared radiation plus panel heater. Figure 1 shows an example of recommended temperature profile for infrared reflow.

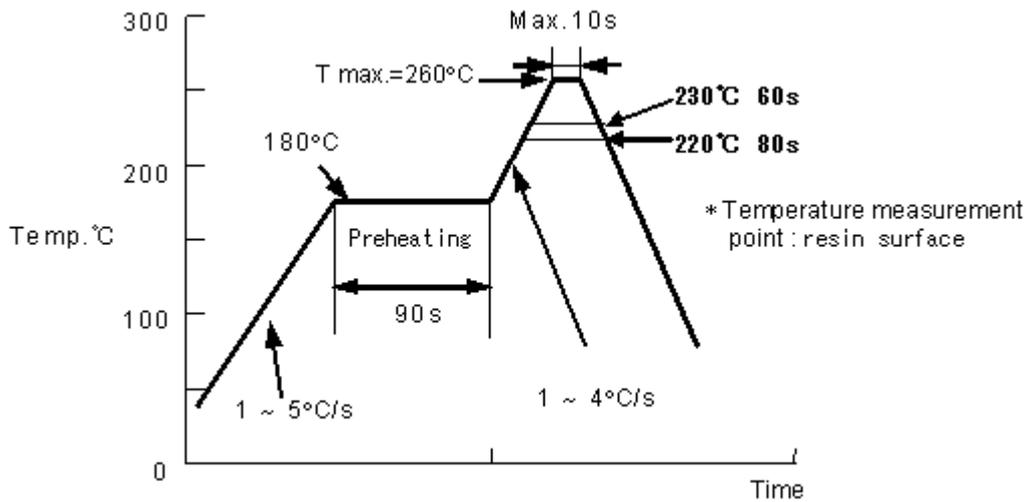


Figure 1 Recommended temperature profile of infrared reflow

Solder dipping

Solder dipping gives larger thermal stress to packages compared to infrared reflow. Preheating is indispensable to relax the thermal stress. Figure 2 shows an example of recommended temperature profile of solder dipping.

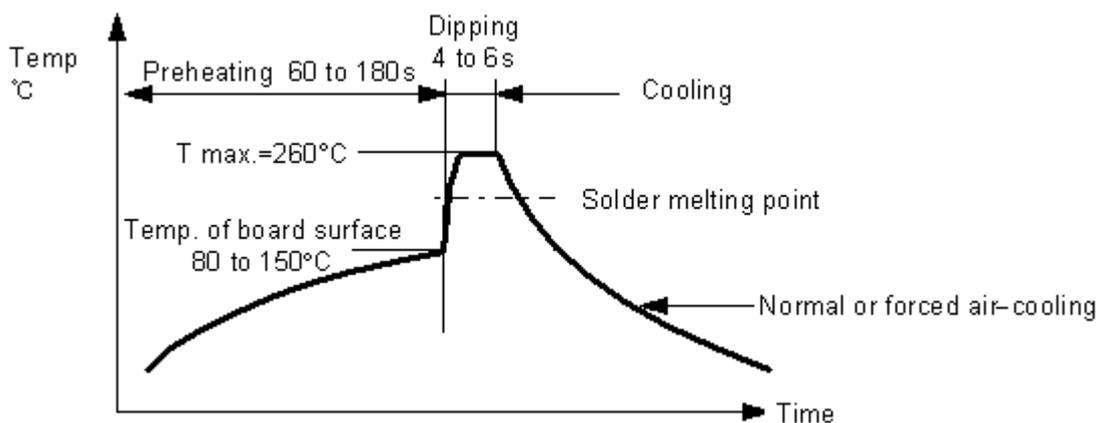


Figure 2 Recommended temperature profile of solder dipping